

L Number	Hits	Search Text	DB	Time stamp
1	418	graybill.xp.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 20:02
2	933040	chip die	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 20:02
3	301	graybill.xp.xa. and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 20:12
4	7	("4835598" "5130771" "5640048" "5959356" "6206997" "6282094" "6325272").PN.	USPAT	2003/08/27 20:05
5	0	6528882.URPN.	USPAT	2003/08/27 20:06
6	0	6528882.URPN.	USPAT	2003/08/27 20:06
7	241	graybill.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 20:13
8	186	graybill.xa. and (chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 20:13
9	5	("4786954" "4972248" "5286671" "5298767" "5666833").PN.	USPAT	2003/08/27 20:17
10	10	5401672.URPN.	USPAT	2003/08/27 20:18
11	7	("4394712" "4893174" "4939568" "5034347" "5401672" "5447871" "5627106").PN.	USPAT	2003/08/27 20:24
-	286	257/276	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/22 18:47
-	13	(circular adj pads) with ((square rectangular) adj pads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 14:10

-	253	257/276 n t (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 14:14
-	0	(thermal! adj via) and (257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 14:15
-	2279077	via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 14:15
-	158	(257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) and via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	7865	calorific adj value	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	0	(calorific adj value) and (257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	617766	transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:17
-	166	(calorific adj value) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 17:18
-	148	((calorific adj value) and transistor) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:22
-	54641	bipolar adj transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:24

-	66629	heatsink heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:24
-	91	(bipolar adj transistor) with (heatsink heat adj sink)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:25
-	81	((bipolar adj transistor) with (heatsink heat adj sink)) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 18:32
-	94	(257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) not (((257/276 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) and via) ((calorific adj value) and transistor) (((bipolar adj transistor) with (heatsink heat adj sink)) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) (@ad>20010520 @rlad>20010520 @pt1d>20010520))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 19:00
-	1	"5757081".PN.	USPAT	2003/08/25 18:48
-	9	("4764804" "4972250" "5091331" "5170930" "5229643" "5272104" "5352926" "5397917" "5426072").PN.	USPAT	2003/08/25 18:49
-	40	("3256465" "3343256" "3372070" "3418545" "3445686" "3454835" "3456335" "3462650" "3648131" "3796927" "3798513" "3885196" "3959579" "3962052" "3969745" "3982268" "4074342" "4097890" "4104674" "4188709" "4263341" "4275410" "4368503" "4379307" "4467343" "4528072" "4613891" "4670764" "4720738" "4761681" "4839510" "4862322" "4897708" "4939568" "4954875" "5198695" "5200631" "5202754" "5404044" "5481133").PN.	USPAT	2003/08/25 18:51
-	27	("2627545" "2734154" "3197766" "3475660" "3561110" "3648131" "3769702" "3813773" "3858958" "3867759" "3904934" "3967162" "3999105" "4029375" "4037246" "4050756" "4129881" "4295700" "4368106" "4394712" "4437109" "4499655" "4509099" "4558396" "4574331" "4581679" "4596069").PN.	USPAT	2003/08/25 18:57

-	56	3648131.URPN.	USPAT	2003/08/25 19:00
-	56	3648131.URPN. n t (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/08/25 19:07
-	1	"3969745".PN.	USPAT	2003/08/25 19:09
-	5	5438212.URPN.	USPAT	2003/08/25 19:09
-	111	(thermal! adj via) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/25 19:10
-	89	((thermal! adj via) and transistor) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 12:36
-	7	("4739448" "5182632" "5485036" "5703753" "5719750" "5825628" "5990545").PN.	USPAT	2003/08/25 19:27
-	1	2002-476940.NRAN.	DERWENT	2003/08/25 19:49
-	1	1998-545315.NRAN.	DERWENT	2003/08/25 19:52
-	10	2325082.URPN.	USPAT	2003/08/25 19:53
-	179	257/625	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:04
-	167	257/502	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:04
-	1401359	@ad>20010520 @rlad>20010520 @pt1d>20010520	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:05
-	152	257/502 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:10

-	237	257/579	U PAT; US-P PUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:10
-	229	257/579 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:11
-	596648	stagger\$ offset\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:11
-	16	(257/579 not (@ad>20010520 @rlad>20010520 @pt1d>20010520)) and (stagger\$ offset\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:13
-	322715	257/\$.ccls. 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:16
-	3036402	heat thermal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:17
-	16090	(stagger\$ offset\$) with (heat thermal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:18
-	828	(257/\$.ccls. 438/\$.ccls.) and ((stagger\$ offset\$) with (heat thermal))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:18
-	593656	transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:18
-	338	((257/\$.ccls. 438/\$.ccls.) and ((stagger\$ offset\$) with (heat thermal))) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:23

-	139	257/164	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:23
-	7421	257/163-166,197,198,557-593,e29.03,e29.011,e29.012,cls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:29
-	13	((stagger\$ offset\$) with (heat thermal)) and 257/163-166,197,198,557-593,e29.03,e29.011,e29.012,cls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 13:30
-	12	(((stagger\$ offset\$) with (heat thermal)) and 257/163-166,197,198,557-593,e29.03,e29.011,e29.012,cls.) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:41
-	7	("2929006" "3252063" "3582723" "3783349" "3878550" "4441116" "4618781").PN.	USPAT	2003/08/26 13:33
-	7	5003370.URPN.	USPAT	2003/08/26 13:52
-	1		USPAT	2003/08/26 13:55
-	615981	plated adj heat! adj sink phs	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:42
-	594568	transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:42
-	5622	(plated adj heat! adj sink phs) and transistor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:43
-	1460204	semiconductor (integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:43
-	1475199	semiconductor integrated adj circuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:44

-	17649	semi ndu t r adj circuit	U PAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:45
-	1442912	(semiconductor (integrated adj circuit)) not (semiconductor adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:45
-	1457550	(semiconductor integrated adj circuit) not (semiconductor adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 16:46
-	14995	(semiconductor integrated adj circuit) not (semiconductor (integrated adj circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:03
-	0	(semiconductor (integrated adj circuit)) not (semiconductor integrated adj circuit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:03
-	564	thermall adj via	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:39
-	15	(plated adj heatl adj sink phs) and (thermal! adj via)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:39
-	12	((plated adj heatl adj sink phs) and (thermal! adj via)) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:53
-	8458	257/706,707,712-722.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:54
-	85	(thermal! adj via) and 257/706,707,712-722.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 17:54

-	75	((thermall adj via) and 257/706,707,712-722.ccls.) n t (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 18:14
-	49	(plated adj heat! adj sink phs) and 257/706,707,712-722.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 18:14
-	44	((plated adj heat! adj sink phs) and 257/706,707,712-722.ccls.) not (@ad>20010520 @rlad>20010520 @pt1d>20010520)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/26 18:14
-	2	5864169.URPN.	USPAT	2003/08/26 18:19
-	1	"5757081".PN.	USPAT	2003/08/26 18:27
-	0	6259156.URPN.	USPAT	2003/08/26 18:28
-	47	shirakawa-kazuhiko.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/27 20:02